



## **CyberOptics Presents Proven Methodologies for Identifying and Resolving Airborne Particle Issues at EMLC 2015**

**Eindhoven, The Netherlands** —June 22, 2015— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will present at the 31<sup>st</sup> European Mask and Lithography Conference, EMLC 2015, at The Pullman Hotel 22-23, June 2015 in Eindhoven. The two-day conference focuses on the science, technology, engineering and application of mask and lithography technologies and associated processes.

Allyn Jackson, field application engineer at CyberOptics, will share insights, best practices and technical know-how for quickly identifying and resolving particles in photo lithography environments. Poster Sessions take place on Monday, 22 June 2015, from 17:30 – 18:40 at the Winteruin Hall in the Technical Exhibition.

“Minimizing airborne particles in lithography applications remains a challenge if using traditional surface scan reticles, in-situ or hand-held methods. Legacy methods such as these lack real-time feedback, and often unexpected particle sources go undetected for hours or even days before finally identified,” said Jackson. “CyberOptics will review the advantages of using the wireless reticle-like particle counter method as a more efficient and effective means of quickly identifying, locating and troubleshooting airborne particles in real-time.”

CyberOptics ReticleSense® Airborne Particle Sensor Quartz (APSRQ) was designed and developed for use with scanners and steppers in semiconductor fabs and has all of the necessary alignment marks and bar codes for broad compatibility. The APSRQ can be loaded directly into a scanner just like a quartz reticle, and travel the entire reticle path to detect in real-time when and where particles occur.

Lithography engineers can rely on CyberOptics ReticleSense proprietary technology, which is an extension of the proven WaferSense® wafer-shaped Airborne Particle Sensor (APS) device in use at semiconductor fabs worldwide including the three largest manufacturers where a contamination-free environment is critical.

WaferSense and ReticleSense Airborne Particle Sensors enable equipment engineers to shorten equipment qualification, release to production and maintenance cycles, all while reducing expenses. Customers have experienced up to 88% time savings, up to 95% reduction in costs, and up to 20X the through-put with half the manpower resource requirements using the WaferSense or ReticleSense sensors relative to legacy surface scan wafer methods.

### **About the WaferSense and ReticleSense Line**

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS) and the Airborne Particle Sensor (APS) are available now in 200mm, 300mm and 450mm wafer sizes. Additionally, both APS and ALS are available in 150mm sizes. The ReticleSense Airborne Particle Sensor (APSR), the

ReticleSense Auto Leveling System (ALSR) and the new ReticleSense Airborne Particle Sensor Quartz (APSRQ) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI; forecasts for at least 10% growth in sales and break-even operating results for 2015 and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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